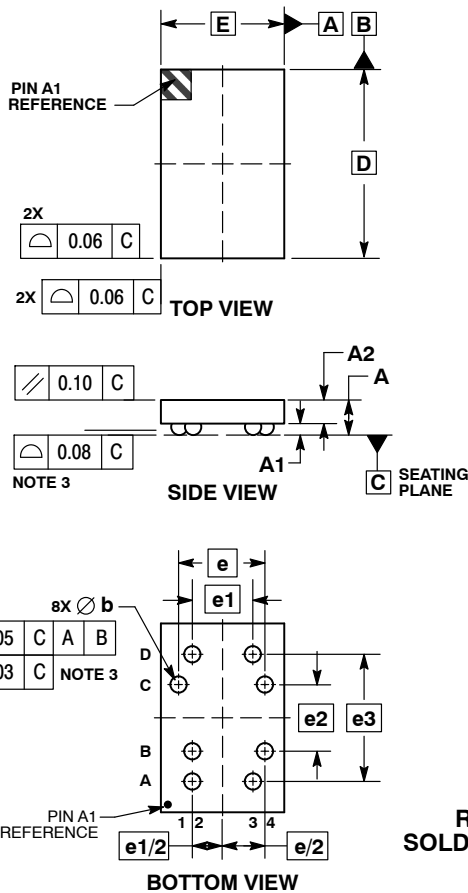


SCALE 4:1

WLCSP8, 3.12x2.04
CASE 567NM
ISSUE O

DATE 08 MAR 2016

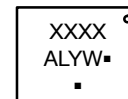


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. DIMENSION b IS MEASURED AT THE MAXIMUM BALL DIAMETER PARALLEL TO DATUM C.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.58
A1	0.16	0.22
A2	0.33 REF	
b	0.22	0.32
D	3.12 BSC	
E	2.04 BSC	
e	1.40 BSC	
e1	1.00 BSC	
e2	1.10 BSC	
e3	2.10 BSC	

GENERIC MARKING DIAGRAM*

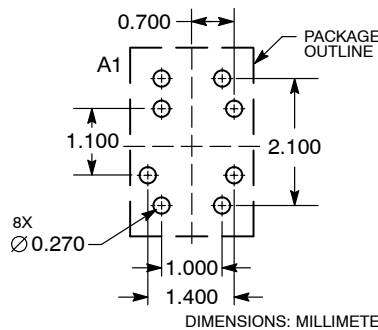


- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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